ABSTRACT

METHOD AND APPARATUS FOR PROVIDING VOID STRUCTURES

The present invention relates to integrated circuits. In particular, but not exclusively, the invention relates to a method and apparatus for connecting elements of integrated circuits with interconnects having one or more voids formed between adjacent interconnects. Embodiments of the invention provide apparatus for connecting elements in an integrated circuit device, comprising: at least one interconnect comprising one or more sidewalls; an interconnect sidewall spacer element arranged to provide structural support to the interconnect and formed on at least one of the interconnect sidewalls; and at least one void adjacent said interconnect and extending from the sidewall spacer element.

Fig. 8